

In the Claims:

Please cancel claims 16 and 17.

Please amend claims 1, 15, and 18 to read as follows:

1. (Amended) A method of producing suspended elements for electrical connection between two portions of a micro-mechanism that can move relative to one another on a semiconductor wafer, the method comprising: forming a layer of sacrificial material that comprises a thin film with at least one adhesive side that is applied dry to a surface of the micro-mechanism, forming electrical connection elements on the layer of sacrificial material, and removing the layer of sacrificial material beneath the electrical connection elements with the electrical connection elements suspended between the two portions of the micro-mechanism that can move relative to one another.

15. (Amended) A method of producing suspended elements between two portions of a micro-mechanism that move relative to one another on a semiconductor wafer, the method comprising:

applying the adhesive side of a dry film over the micro-mechanism on the semiconductor wafer to immobilize the moveable components without penetrating any cavities therein;

forming electrical connection elements on the layer of sacrificial material; and

removing the layer of sacrificial material beneath the electrical connection elements to leave the electrical connection elements suspended between the two portions of the micro-mechanism that move relative to one another.

18. (Amended) A method of producing suspended elements between two portions of a micro-mechanism containing components that move relative to one another on a semiconductor wafer, the method comprising:

applying the adhesive side of a dry film over the micro-mechanism on the semiconductor wafer to immobilize the moveable components without penetrating any cavities therein;

forming a mask on the dry film;  
depositing, developing, and selectively removing a sacrificial layer from the mask and the dry film to form windows on the dry film;  
opening the windows by selectively etching the dry film;  
depositing a dielectric layer to cover the windows without penetrating any underlying cavities;  
depositing a conductive layer that is attached to at least one moveable portion of the micro-mechanism; and  
selectively removing the conductive layer and the dielectric layer, and removing the dry film to form electrical connection elements suspended between the two portions of the micro-mechanism containing components that move relative to one another.

#### REMARKS

Claims 1-15, and 18-24 are presented for further examination. Claims 16 and 17 have been canceled. Claims 1, 15, and 18 have been amended.

In the Office Action dated August 27, 2002, the Examiner objected to the specification wherein a prior-filed application was incorporated by reference. Applicants have removed the incorporation by reference language.

Claims 1-24 were rejected under 35 U.S.C. § 103(a) as unpatentable over U.S. Patent No. 5,822,856 ("Bhatt et al.") in view of U.S. Patent No. 5,028,983 ("Bickford et al.").

Applicants respectfully disagree with the basis for the rejection and request reconsideration and further examination of the claims.

The disclosed embodiments of the invention are directed to a micro-mechanism having two portions that move relative to one another on a semiconductor wafer and having elements for electrical connections suspended between the two movable portions. In the method, a sacrificial material comprising a thin film having one adhesive side is applied dry to a surface of the micro-mechanism for holding the two movable portions in position, then the electrical connection elements are formed on the layer of sacrificial material, which is then removed so that the electrical connection elements remain suspended between the two portions of the micro-mechanism that can move relative to one another.